

ai could
1 acoustically active portion of the electronic device."

2
3 Please amend claim 5 as follows:

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5 In the first line of the claim, replace the number "2"
6 with the number --3--.

7
8 Please amend claim 11 as follows:

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10 In the third line of the claim, replace the words "at
11 least one" with the word --the--.

12
13 REMARKS

14
15 Reexamination is hereby requested.

16
17 The examiner rejected claims 1-12 under 35 U.S.C. 112,
18 second paragraph, and recited portions of claims 1, 5 and 11 as
19 being indefinite. Claims 1, 5 and 11 have been amended to remove
20 these bases for rejection.

21
22 The examiner rejected claims 1, 2, 7 and 8 under 35 U.S.C.
23 102(a) as being unpatentable over Temple et al. (US 4,905,095).
24 The examiner described Temple as disclosing a die "having a
25 plurality of signal conductors (metallized layer 70)...located on
26 the upper surface of the die" and a lid having "a plurality of
27 lower surface signal conductor pads...located upon the lower
28 surface of the lid"... "wherein each lower surface signal conductor

1 pad is also electrically connected to one of the signal conductor
2 pads on the upper surface of the die...." Although Temple does
3 disclose signal conductors located upon the upper surface of the
4 die, it does not disclose "signal connector pads" located upon the
5 upper surface of the die. Furthermore, Temple does not disclose
6 electrical connections between the signal connector pads located
7 upon the upper surface of the die and any signal connector pads
8 located on the lower surface of the lid. Temple, instead, only
9 discloses electrical connections between signal connector pads
10 located on the lower surface of the lid and signal connector pads
11 located upon the upper surfaces of the devices, which devices, in
12 turn, are mounted upon the upper surface of the die.

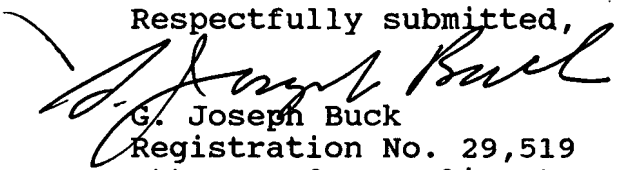
13
14 Claim 1 (as amended) recites: "...each lower surface
15 signal connector pad on the lid being electrically connected to
16 one of the signal connector pads located upon the upper surface of
17 the die...." Similarly, Claim 11 recites: "the lower surface
18 signal connector pad on the lid being electrically connected to
19 the signal connector pad located upon the upper surface of the
20 die...." As a consequence, it is respectfully submitted that the
21 disclosure in Temple does not render claims 1 and 11, and the
22 claims dependent thereon, obvious.

23
24 As set forth in the preceding remarks, it is believed
25 that the examiner's bases for rejecting the claims have been
26 traversed, and allowance of claims 1 through 12 is hereby
27 requested.
28

1 If the examiner has any questions, it would be appreciated
2 if the examiner would contact G. Joseph Buck at (310) 540-8840.

3
4 No additional fee is seen to be required.

5
6 Respectfully submitted,

7 
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